



SPECIFICATION

(Reference sheet)

· Supplier : Samsung electro-mechanics · Samsung P/N : CL31B106KAHSFNE

· Product : Multi-layer Ceramic Capacitor · Description : CAP, 10uF, 25V, ±10%, X7R, 1206

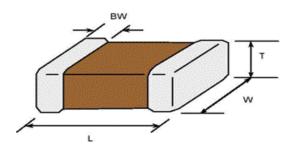
A. Samsung Part Number

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1	Series	Samsung Multi-layer Ceramic Capacitor			
2	Size	1206 (inch code)	$L: 3.20 \pm 0.20 \text{ mm}$	W : $1.60 \pm 0.20 \text{ mm}$	
(3)	Dielectric	X7R	Inner electrode	Ni	
	Dielectric	ATK	8 Illier electrode	INI	
4	Capacitance	10 uF	Termination	Soft termination	
⑤	Capacitance	±10 %	Plating	Sn 100% (Pb Free)	
	tolerance		Product	Product for POWER application	
6	Rated Voltage	25 V	Special	Reserved for future use	
7	Thickness	1.60 ± 0.20 mm	① Packaging	Embossed Type, 7" reel	

B. Structure & Dimension



Samsung P/N	Dimension(mm)				
Samsung F/N	L	W	Т	BW	
CL31B106KAHSFNE	3.20 ± 0.20	1.60 ± 0.20	1.60 ± 0.20	0.50 ± 0.30	

C. Samsung Reliablility Test and Judgement Condition

	Judgement	Test condition		
Capacitance With	in specified tolerance	1kHz ±10% / 1.0±0.2Vrms		
Tan δ (DF)	0.1 max.	*A capacitor prior to measuring the capacitance is heat treated at 150 ℃+0/-10 ℃ for 1hour and maintained in ambient air for 24±2 hours.		
Insulation 10,0	00Mohm or 100Mohm× <i>µ</i> F	Rated Voltage 60~120 sec.		
Resistance Whi	ichever is smaller			
Appearance No a	bnormal exterior appearance	Microscope (×10)		
Withstanding No d	lielectric breakdown or	250% of the rated voltage		
Voltage mecl	hanical breakdown			
Temperature X7R				
Characteristics (From	m-55 $^{\circ}$ to 125 $^{\circ}$, Capacitance change s	hould be within ±15%)		
Adhesive Strength No p	eeling shall be occur on the	500g·f, for 10±1 sec.		
of Termination term	inal electrode			
Bending Strength Capa	acitance change : within ±12.5%	Bending to the limit (1mm)		
		with 1.0mm/sec.		
Solderability More	e than 75% of terminal surface	SnAg3.0Cu0.5 solder		
is to	be soldered newly	245±5°C, 3±0.3sec.		
		(preheating : 80~120°C for 10~30sec.)		
Resistance to Capa	acitance change : within ±7.5%	Solder pot : 270±5°C, 10±1sec.		
Soldering Heat Tan	δ, IR : initial spec.			
I -	acitance change : within ± 5% δ, IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours × 3 direction (x, y, z)		
Moisture Capa	acitance change: within ±12.5%	With rated voltage		
Resistance Tan	δ: 0.125 max	40±2°C, 90~95%RH, 500+12/-0hrs		
IR:	500Mohm or 12.5Mohm × μ F Whichever is smaller			
High Temperature Capa	acitance change : within ±12.5%	With 150% of the rated voltage		
Resistance Tan	δ: 0.125 max	Max. operating temperature		
IR:	1,000Mohm or 25Mohm × μ F Whichever is smaller	1,000+48/-0hrs		
Temperature Capa	acitance change: within ±7.5%	1 cycle condition		
	δ, IR : initial spec.	Min. operating temperature → 25°C		
	·	→ Max. operating temperature → 25°C		
		5 cycle test		

D. Recommended Soldering method:

Reflow (Reflow Peak Temperature : 260±5°C, 30sec.)



Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.